

□ MN101E13G

| Type | MN101E13G | MN101EF13G |
|------------------------------------|---|--|
| Internal ROM type | Mask ROM | FLASH |
| ROM (byte) | 128K | |
| RAM (byte) | 4K | |
| Package (Lead-free) | QFP084-P-1818E | QFP084-P-1818E (ES (Engineering Sample) available) |
| Minimum Instruction Execution Time | 100 ns (at 3.135 V to 3.465 V, , normal-mode) | 100 ns |

■ Interrupts

External (7 lines)

Internal (13 lines) : Timer × 4, A/D × 1, RESET × 1, OSD × 1, Serial × 2, I²C × 1, Caption × 1, Remote control × 1, HSYNC × 1, VSYNC × 1

■ Timer Counter

8-bit timer × 4

Watchdog timer : Time-out period is selectable.

■ Serial interface

I²C × 1 : for multimaster mode, bus line (output) has 2 systems

Sync serial / UART × 1

■ Caption / Teletext Decoder

• Built-in sync separator × 1

■ I/O Pins

| I/O | 35 | Common use |
|-----|----|------------|
| | | |

■ A/D converter

10-bit × 8-ch. (with S/H)

■ PWM

8-bit × 6-ch. , 14-bit × 1-ch.

■ Special Ports

Remote control reception

■ CRTC

1-layer display (graphics, characters, splits)

■ Notes

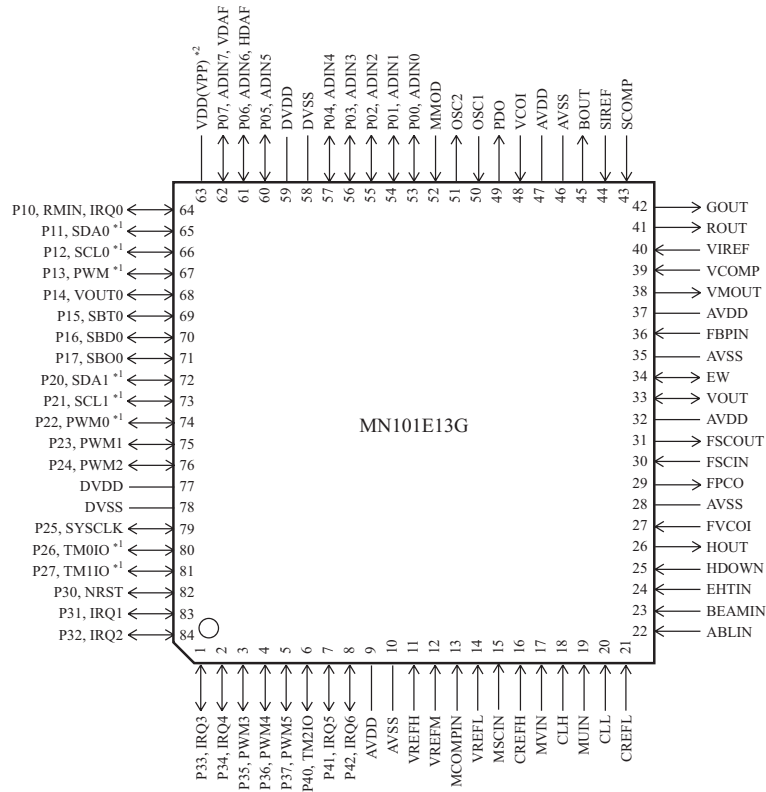
Remote control input discriminant circuit built-in, build-in NTSC video signal processing circuit, built-in 3-line comb filter

■ Development tools

In-circuit Emulator

PX-PAC101E02-4W9J

■ Pin Assignment



QFP084-P-1818E

Note) *1: 1.5 V dielectric N-ch. open drain output pin
 *2: Mask ROM = VDD, Flash memory built-in type = VPP

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